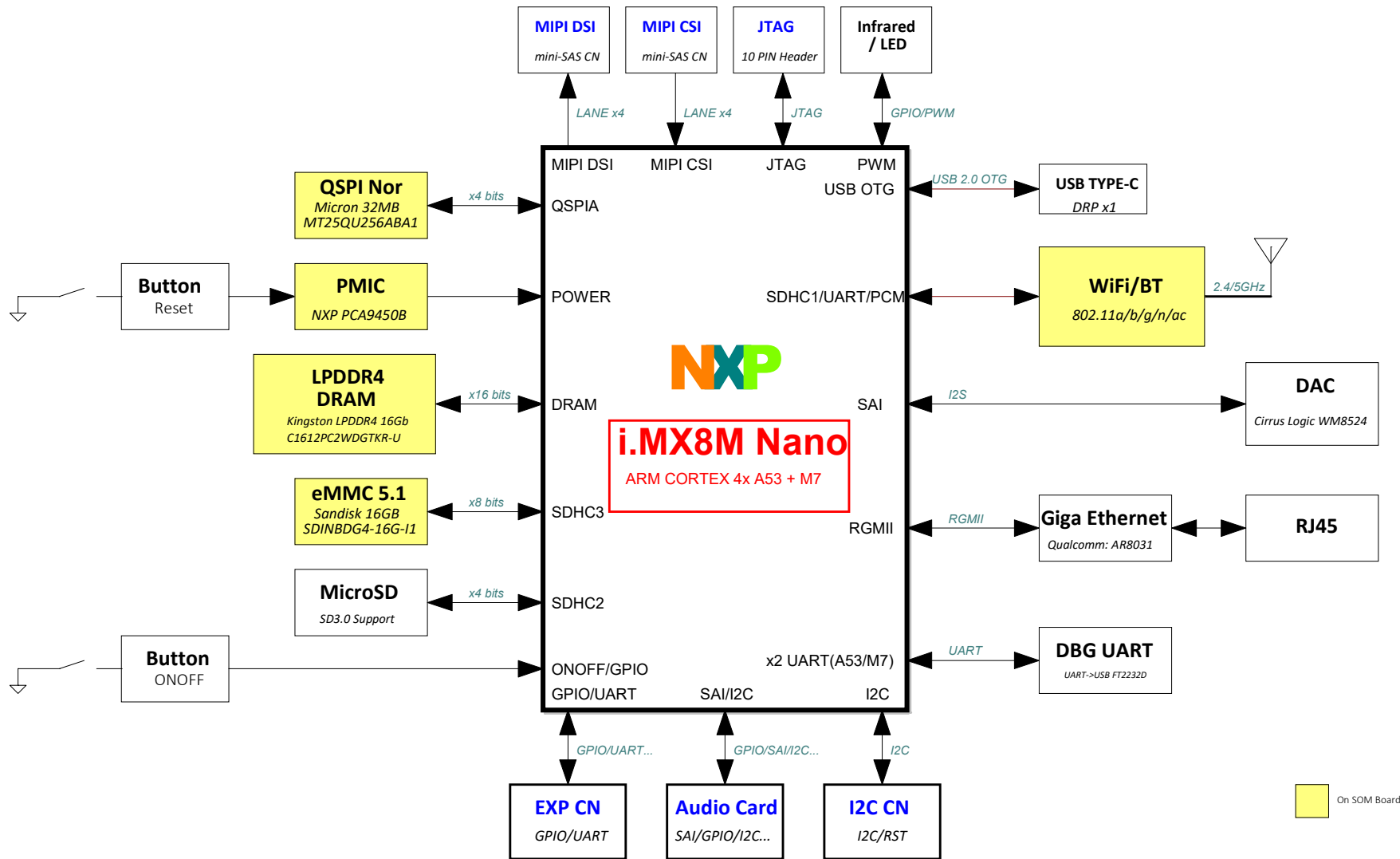
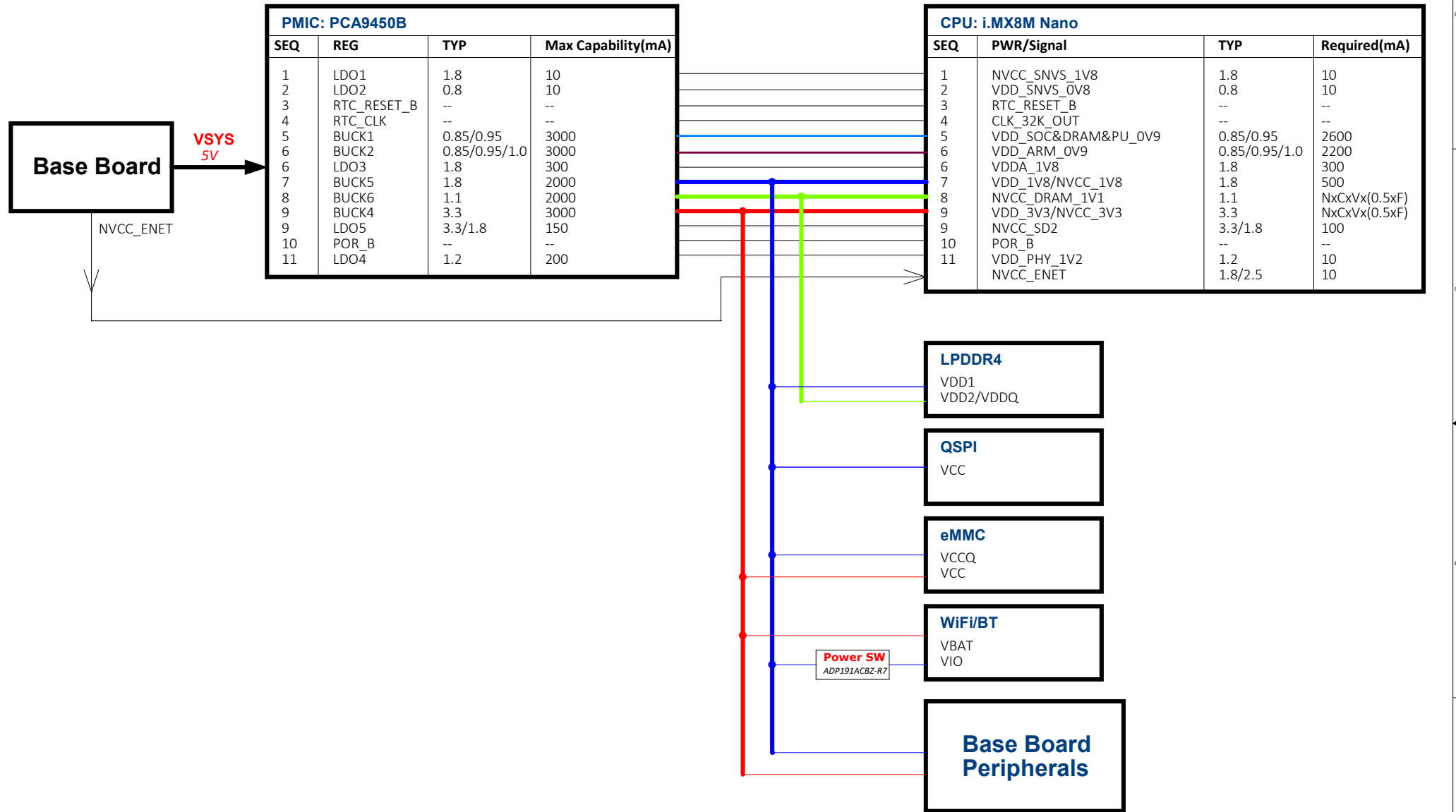


X-815LPD4-EVKCY Block Diagram

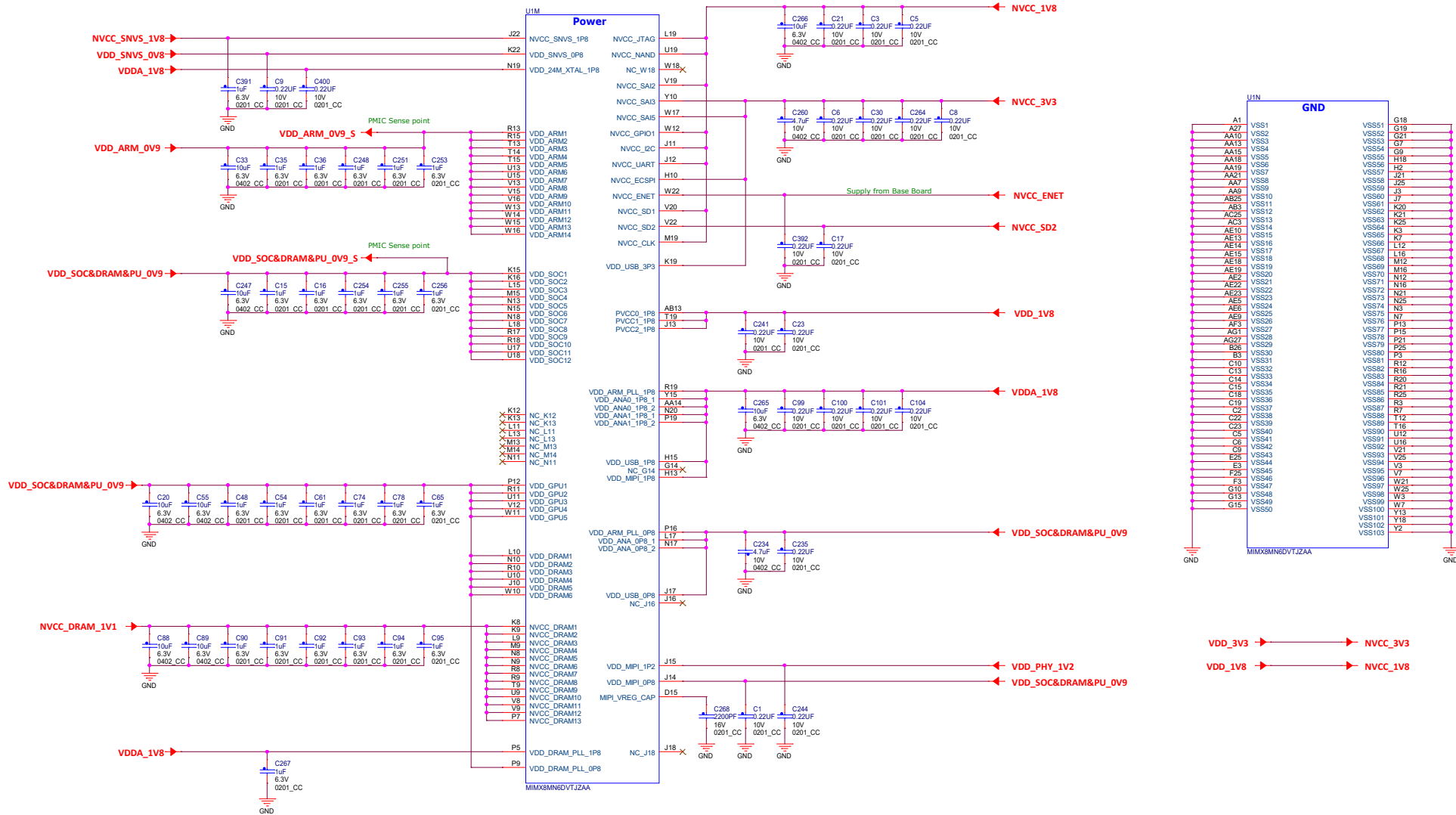


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Drawn by: Mac Zhang		Page Title: Block Diagram	
Approved: <Approver>	Size C	Document Number SCH-46441 PDF: SPF-46441	Rev A1
Date: Tuesday, November 05, 2019		Sheet 2 of 13	

815LPD4-EVKCY PWR TREE



i.MX8M Nano PWR

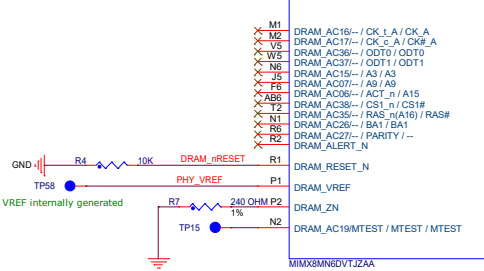
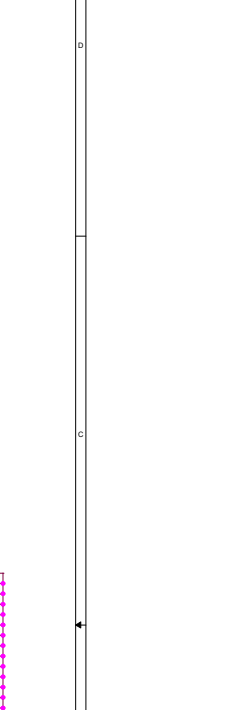
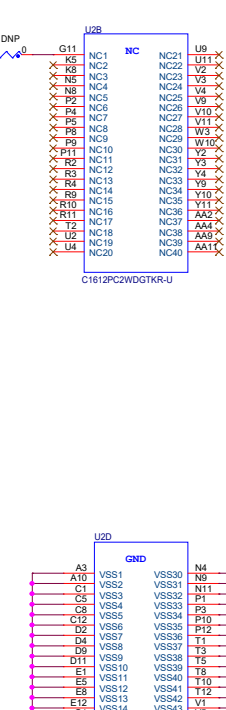
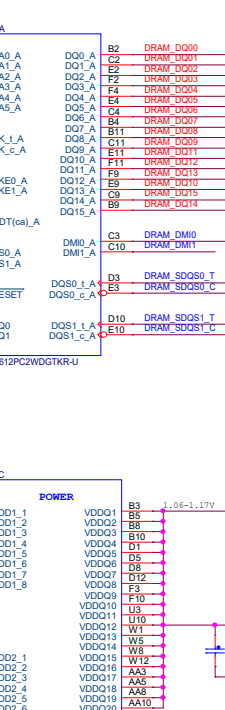
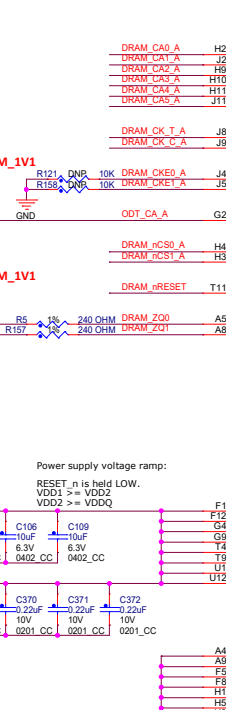
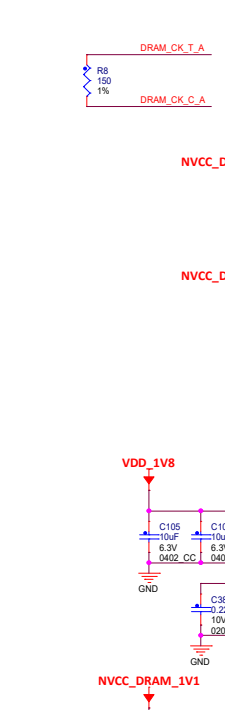
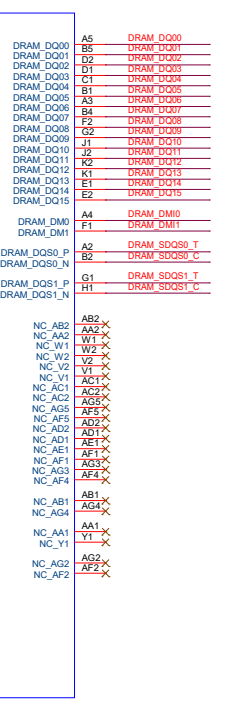
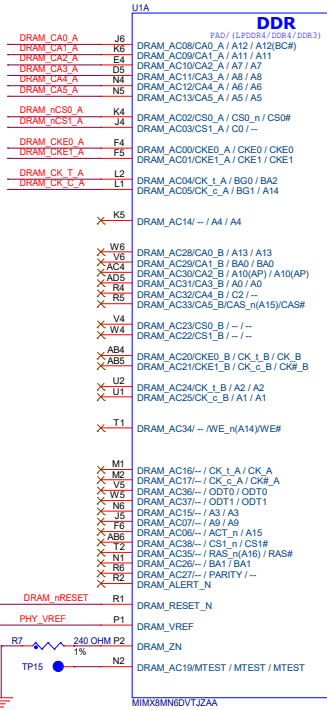


U1M	U1M	U1M	U1M
A1	VSS1	VSS51	G18
A27	VSS2	VSS52	G19
AA10	VSS3	VSS53	G21
AA13	VSS4	VSS54	G7
AA15	VSS5	VSS55	G9
AA18	VSS6	VSS56	H2
AA19	VSS7	VSS57	J21
AA21	VSS8	VSS58	J23
AA7	VSS9	VSS59	J30
AA9	VSS10	VSS60	J7
AB5	VSS11	VSS61	K20
AC3	VSS12	VSS62	K21
AC5	VSS13	VSS63	K25
AE10	VSS14	VSS64	K3
AE13	VSS15	VSS65	K7
AE14	VSS16	VSS66	L12
AE15	VSS17	VSS67	L16
AE18	VSS18	VSS68	M12
AE19	VSS19	VSS69	M16
AE2	VSS20	VSS70	N12
AE22	VSS22	VSS72	N16
AE3	VSS23	VSS73	N25
AE5	VSS24	VSS74	N3
AE6	VSS25	VSS75	N3
AE9	VSS26	VSS76	P13
AF3	VSS27	VSS77	P15
AG27	VSS28	VSS78	P21
B26	VSS29	VSS79	P25
B3	VSS30	VSS80	P5
C10	VSS31	VSS81	R12
C13	VSS32	VSS82	R16
C14	VSS33	VSS83	R20
C15	VSS34	VSS84	R25
C18	VSS35	VSS85	R3
C19	VSS36	VSS86	R3
C2	VSS37	VSS87	R7
C22	VSS38	VSS88	T12
C23	VSS39	VSS89	T16
C5	VSS40	VSS90	U12
C6	VSS41	VSS91	U16
C9	VSS42	VSS92	V21
E25	VSS43	VSS93	V25
E3	VSS44	VSS94	V3
F25	VSS45	VSS95	V7
F3	VSS46	VSS96	W21
G10	VSS47	VSS97	W25
G13	VSS48	VSS98	W5
G15	VSS49	VSS99	W7
	VSS50	VSS100	Y13
		VSS101	Y18
		VSS102	Y2
		VSS103	

VDD_3V3 → NVCC_3V3
VDD_1V8 → NVCC_1V8

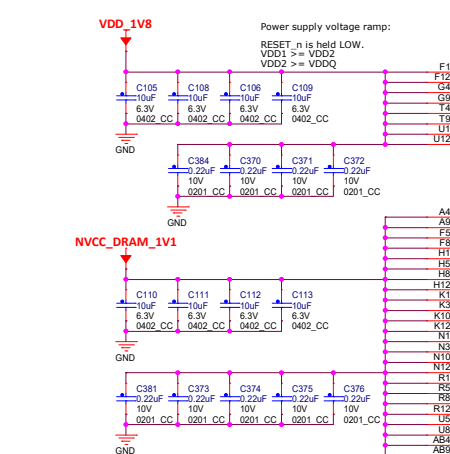
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Drawn by: Mac Zhang		Page Title: GPU PWR	
Approved: <Approver>		Size C	Document Number SCH-46441 PDF: SPF-46441
Date: Tuesday, November 05, 2019		Sheet 4 of 13	Rev A1

LPDDR4 2GB

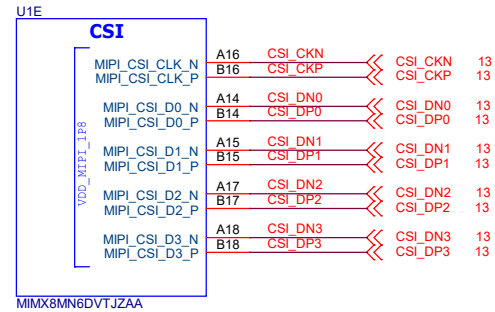
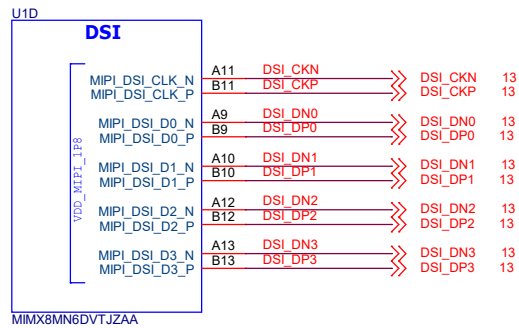
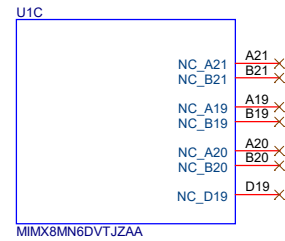
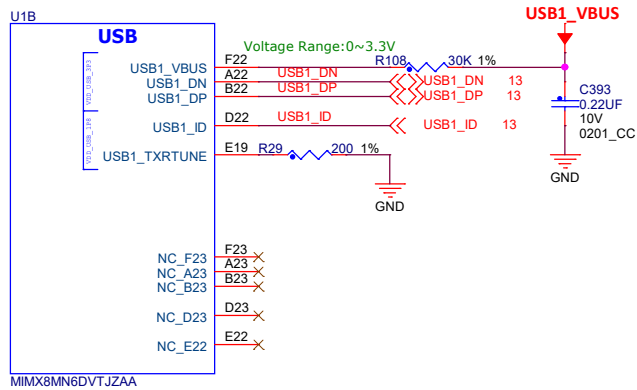


Pin Name	LPDDR4	DDR4
DRAM_DQ00_P	DQ00_LA	DQS_LA
DRAM_DQ00_N	DQ00_CA	DQS_CA
DRAM_DM0	DM0_A	DMU_nA/DBIU_nA
DRAM_DQ01	DO1_A	DO1_A
DRAM_DQ02	DO2_A	DO2_A
DRAM_DQ03	DO3_A	DO3_A
DRAM_DQ04	DO4_A	DO4_A
DRAM_DQ05	DO5_A	DO5_A
DRAM_DQ06	DO6_A	DO6_A
DRAM_DQ07	DO7_A	DO7_A
DRAM_DQ08_P	DQ08_LA	DQS_LA
DRAM_DQ08_N	DQ08_CA	DQS_CA
DRAM_DM1	DM1_A	DMU_nA/DBIU_nA
DRAM_DQ09	DO9_A	DO9_A
DRAM_DQ10	DO10_A	DO10_A
DRAM_DQ11	DO11_A	DO11_A
DRAM_DQ12	DO12_A	DO12_A
DRAM_DQ13	DO13_A	DO13_A
DRAM_DQ14	DO14_A	DO14_A
DRAM_DQ15_P	DQ15_LA	DQS_LA
DRAM_DQ15_N	DQ15_CA	DQS_CA
DRAM_DM2	DM2_A	DMU_nA/DBIU_nA
DRAM_DQ16	DO16_A	DO16_A
DRAM_DQ17	DO17_A	DO17_A
DRAM_DQ18	DO18_A	DO18_A
DRAM_DQ19	DO19_A	DO19_A
DRAM_DQ20	DO20_A	DO20_A
DRAM_DQ21	DO21_A	DO21_A
DRAM_DQ22	DO22_A	DO22_A
DRAM_DQ23	DO23_A	DO23_A
DRAM_DQ24_P	DQ24_LA	DQS_LA
DRAM_DQ24_N	DQ24_CA	DQS_CA
DRAM_DM3	DM3_A	DMU_nA/DBIU_nA
DRAM_DQ25	DO25_A	DO25_A
DRAM_DQ26	DO26_A	DO26_A
DRAM_DQ27	DO27_A	DO27_A
DRAM_DQ28	DO28_A	DO28_A
DRAM_DQ29	DO29_A	DO29_A
DRAM_DQ30	DO30_A	DO30_A
DRAM_DQ31	DO31_A	DO31_A

Pin Name	LPDDR4	DDR4
DRAM_RESET_N	RESET_N	RESET_n
DRAM_ALERT_N	MTST1	ALERT_n/MTST1
DRAM_AC00	CKE0_A	CKE0
DRAM_AC01	CKE1_A	CKE1
DRAM_AC02	CS0_A	CS0_n
DRAM_AC03	CS1_A	CS1_n
DRAM_AC04	CK_T_A	BG0
DRAM_AC05	CK_C_A	BG1
DRAM_AC06	ACT_n	ACT_n
DRAM_AC07	CA0_A	A9
DRAM_AC08	CA1_A	A10
DRAM_AC09	CA2_A	A11
DRAM_AC10	CA3_A	A12
DRAM_AC11	CA4_A	A13
DRAM_AC12	CA5_A	A14
DRAM_AC13	CA6_A	A15
DRAM_AC14	CA7_A	A16
DRAM_AC15	CA8_A	A17
DRAM_AC16	CA9_A	A18
DRAM_AC17	CA10_A	A19
DRAM_AC18	CA11_A	A20
DRAM_AC19	CA12_A	A21
DRAM_AC20	CKE0_B	CKE0_B
DRAM_AC21	CKE1_B	CKE1_B
DRAM_AC22	CS1_B	CS1_B
DRAM_AC23	CS2_B	CS2_B
DRAM_AC24	CK_T_B	A2
DRAM_AC25	CK_C_B	A1
DRAM_AC26	ACT_n	ACT_n
DRAM_AC27	PARITY	PARITY
DRAM_AC28	CA0_B	A18
DRAM_AC29	CA1_B	BAD
DRAM_AC30	CA2_B	A10/AP
DRAM_AC31	CA3_B	AD
DRAM_AC32	CA4_B	CA5_n/A15
DRAM_AC33	CA5_B	WE_n/A14
DRAM_AC34	CA6_B	RAS_n/A16
DRAM_AC35	CA7_B	ODT0
DRAM_AC36	CA8_B	ODT1
DRAM_AC37	CA9_B	ODT2
DRAM_AC38	CA10_B	ODT3
DRAM_ZN	Z0	Z0
DRAM_VREF	VREF	VREF



i.MX8M Nano PHYs



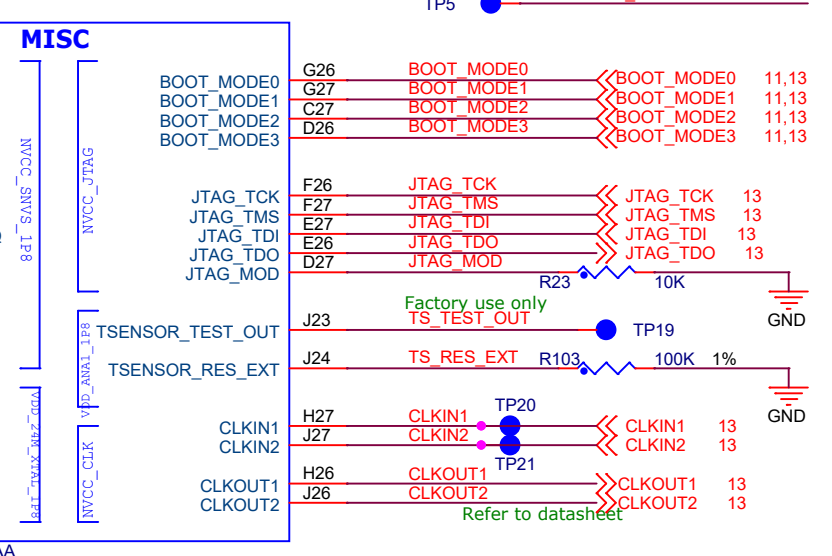
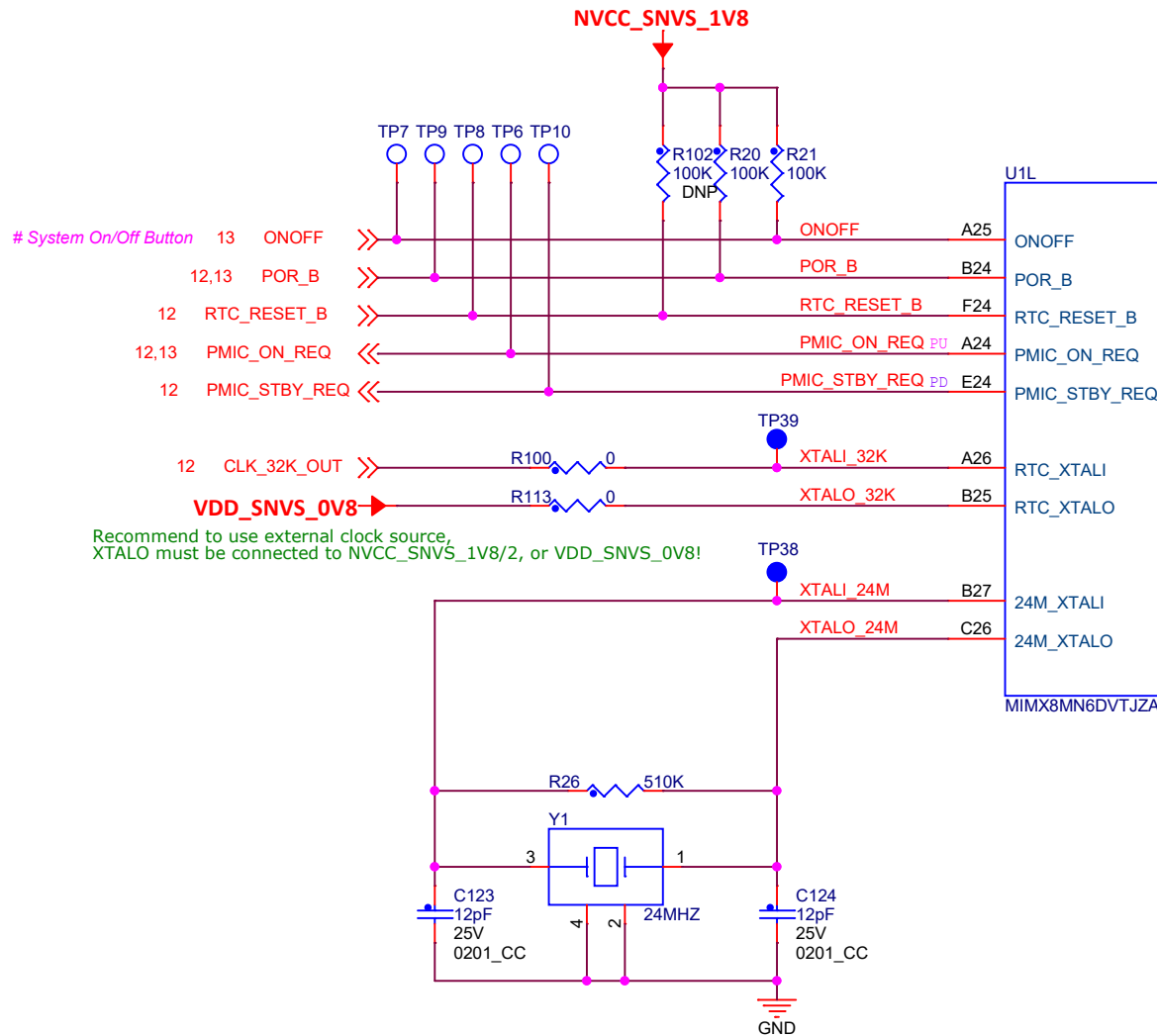
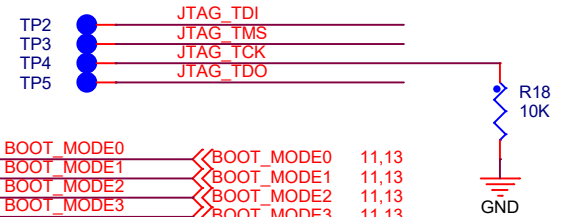
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Drawn by: Mac Zhang	Page Title: CPU PHY		
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i.MX8M Nano MISC

Caution:

JTAG_TMS pin must be connected with a 50ohm serial resistor near the component if used or fanout. Otherwise, floating if not fanout.

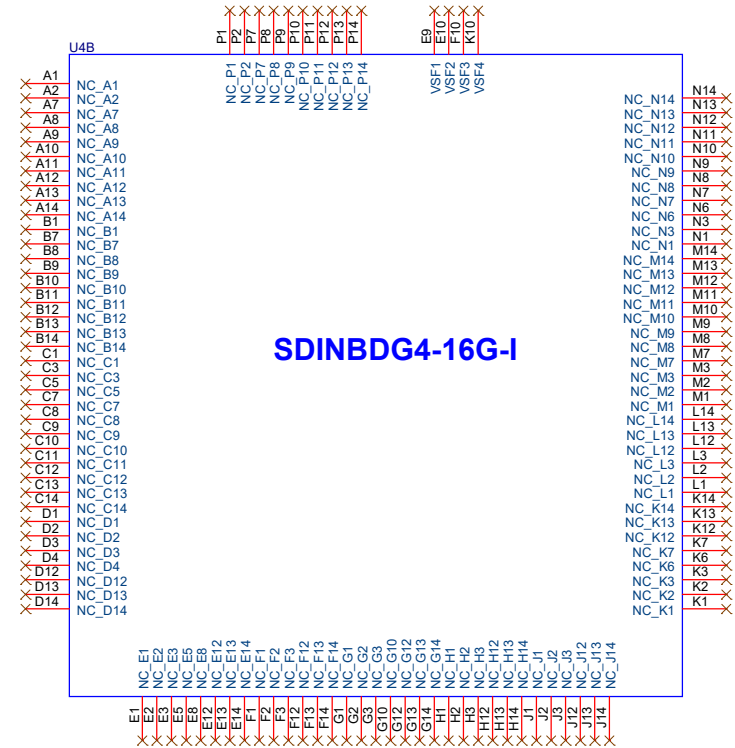
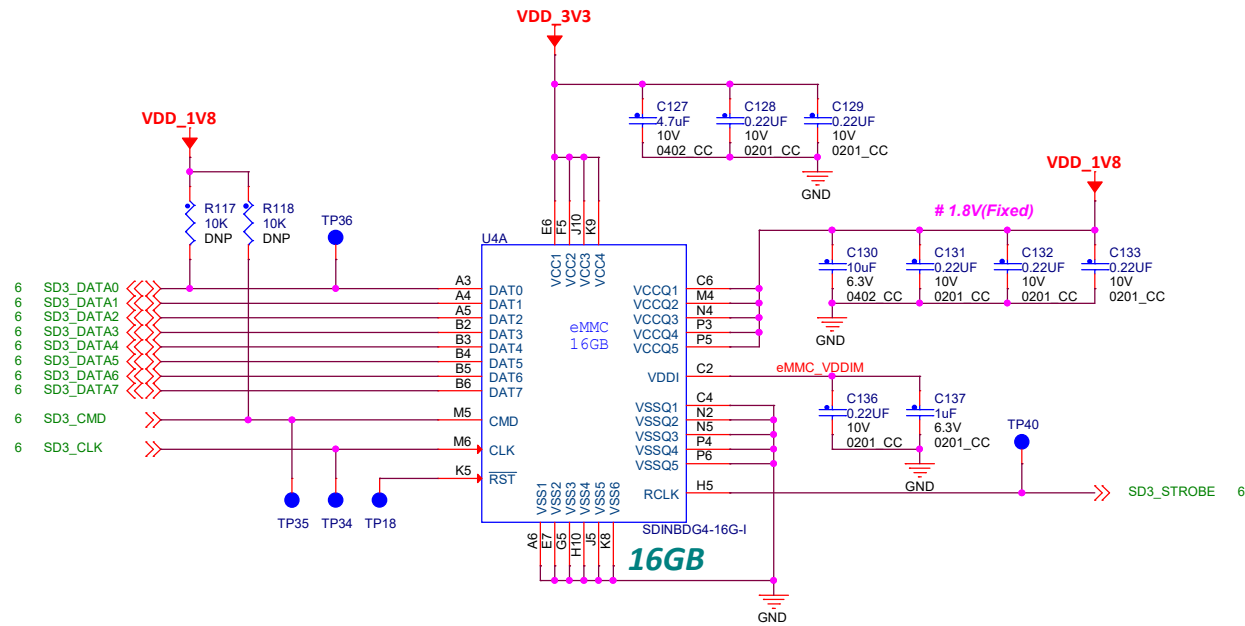
JTAG Debug



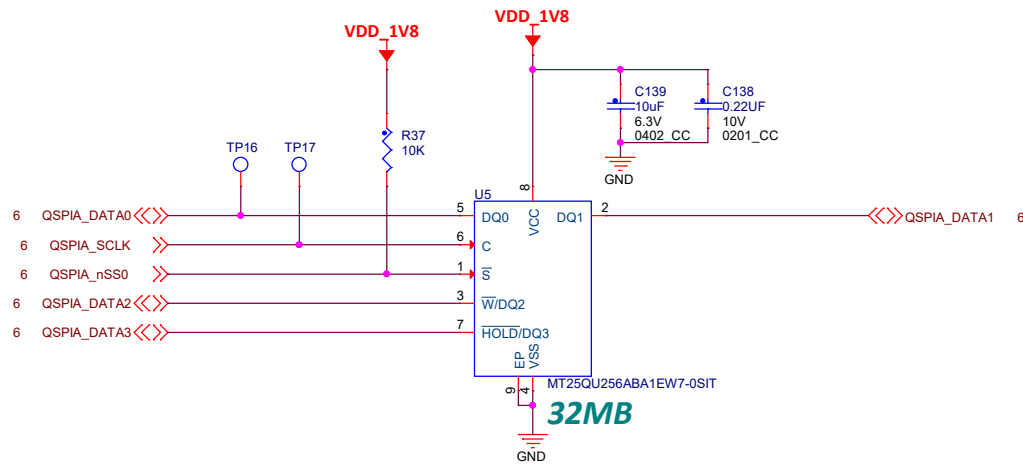
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Storage

eMMC



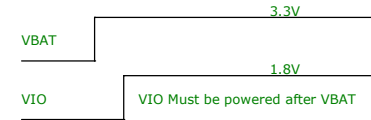
QSPI Flash



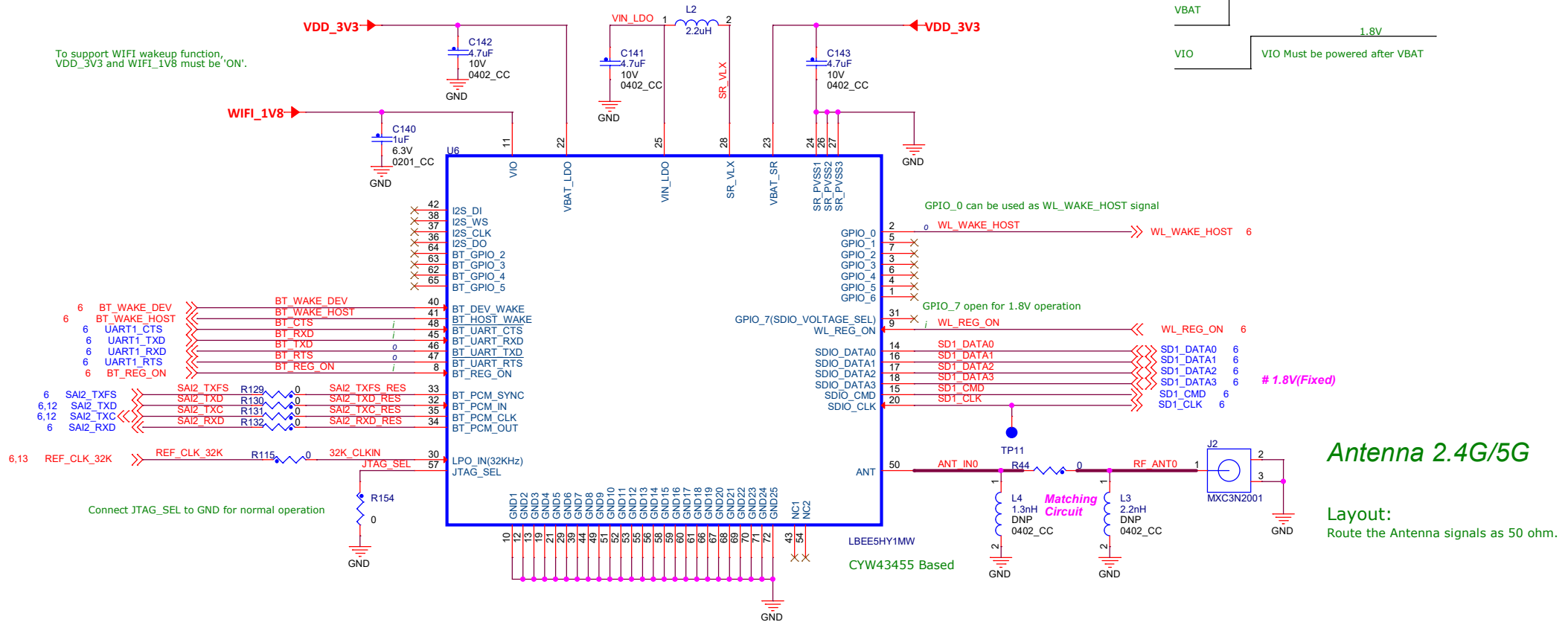
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		Rev A1	

2.4G/5G WIFI/BT Module

Power Sequence



To support WIFI wakeup function, VDD_3V3 and WIFI_1V8 must be 'ON'.

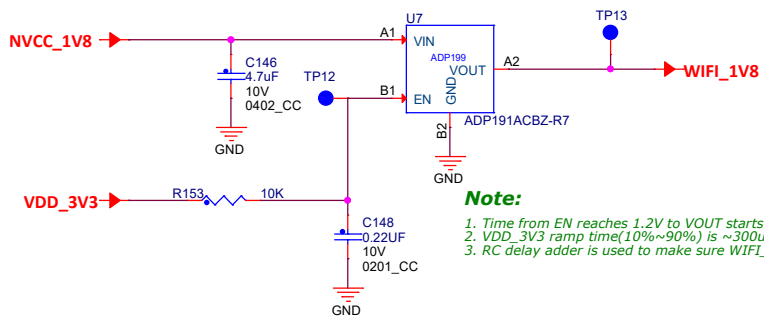


Antenna 2.4G/5G

Layout:
Route the Antenna signals as 50 ohm.

1.8V(Fixed)

LBEE5HY1MW
CYW43455 Based



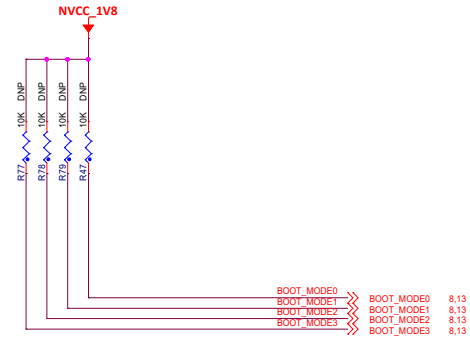
Note:
1. Time from EN reaches 1.2V to VOUT starts ramping is 40us typical
2. VDD_3V3 ramp time(10%~90%) is ~300us
3. RC delay adder is used to make sure WIFI_1V8 powers up after VDD_3V3

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Boot Mode

i.MX8M Nano Boot Mode

BOOT_PIN[3]	BOOT_PIN[2]	BOOT_PIN[1]	BOOT_PIN[0]	Boot Modes
BOOT_MODE3 (TEST_MODE)	BOOT_MODE2 (JTAG_TRST_B)	BOOT_MODE1	BOOT_MODE0	Function
0	0	0	0	Boot From Internal Fuses
0	0	0	1	USB Serial Download
0	0	1	0	USDHC3 (eMMC boot only, SD3 8-bit)
0	0	1	1	USDHC2 (SD boot only, SD2)
0	1	0	0	NAND 8-bit single device 256 page
0	1	0	1	NAND 8-bit single device 512 page
0	1	1	0	QSPI 3B Read
0	1	1	1	QSPI Hyperflash 3.3V
1	0	0	0	ecSPI Boot
1	0	0	1	Reserved
1	0	1	0	Reserved
1	0	1	1	Reserved
1	1	0	0	Reserved (Boot on I2C connected to BOOT PIN[3:2])
1	1	0	1	Reserved
1	1	1	0	Infinite Loop Mode
1	1	1	1	Test Mode

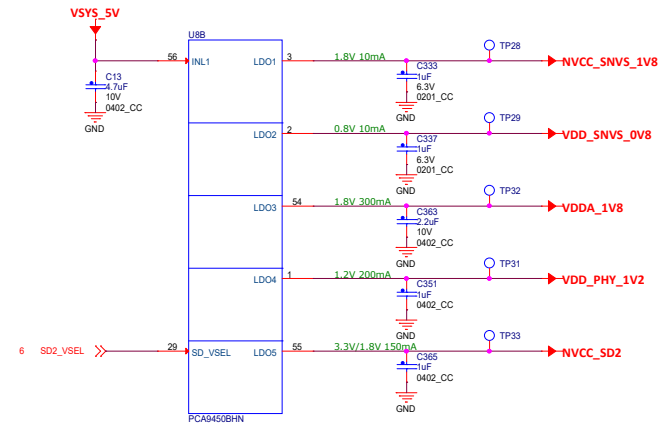
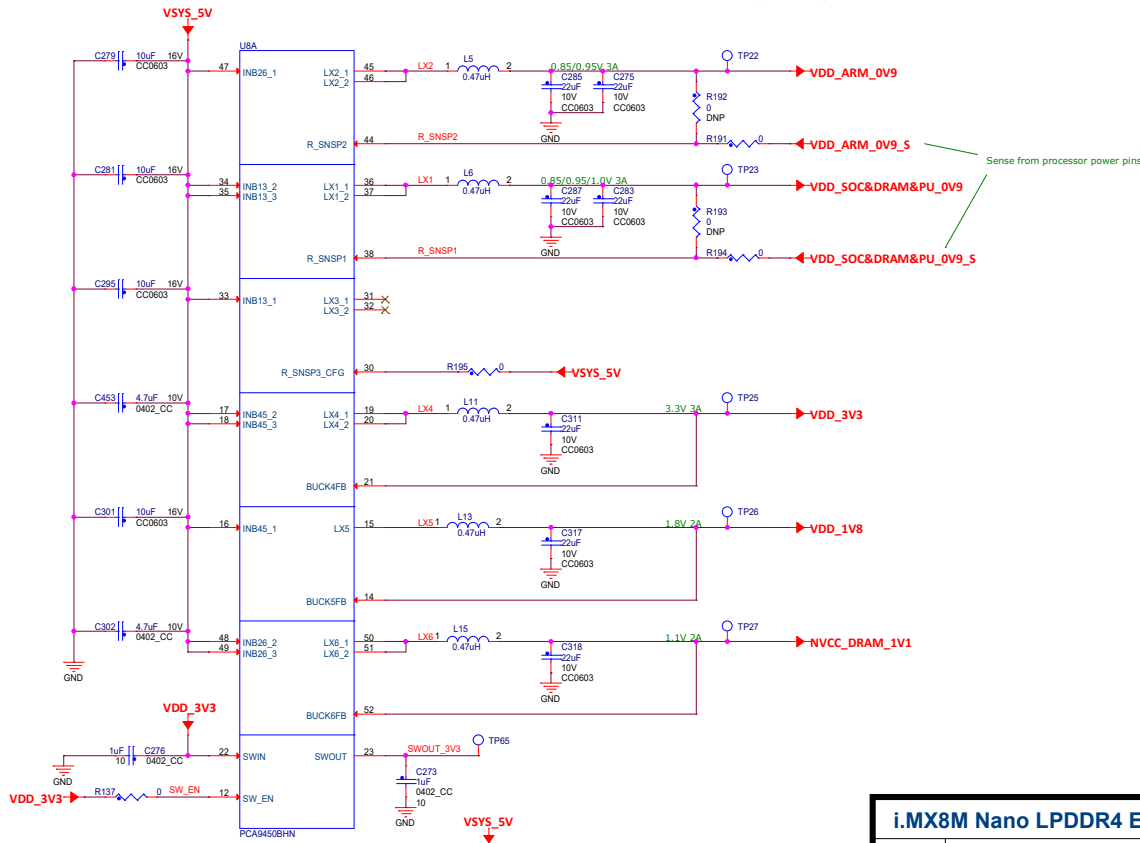


Note:

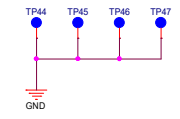
1. BOOT_MODE0-3 signals are used for boot selections
2. BOOT_MODE signals have internal PD before and after POR_B reset is deasserted!
3. When using Base Board for Multi boot selection, you must keep the resistors DNP on SOM board!

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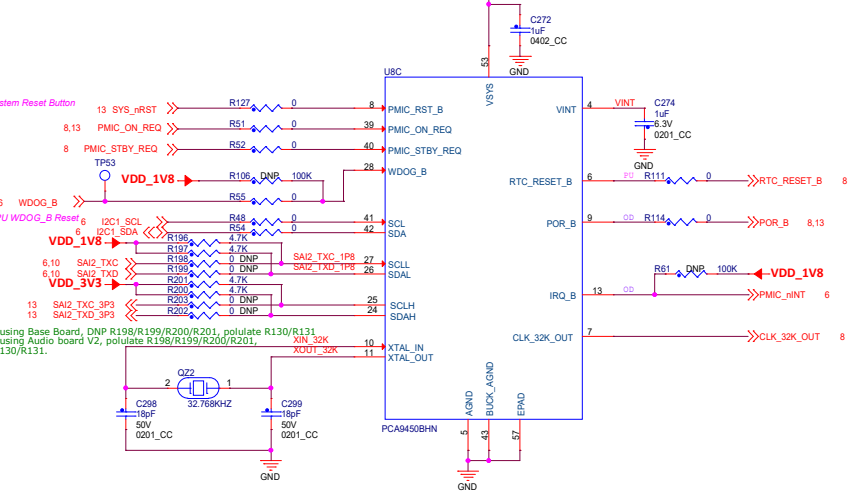
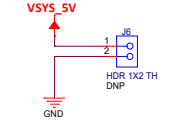
SYS PMIC



GND Testpoints



Backup PWR Supply



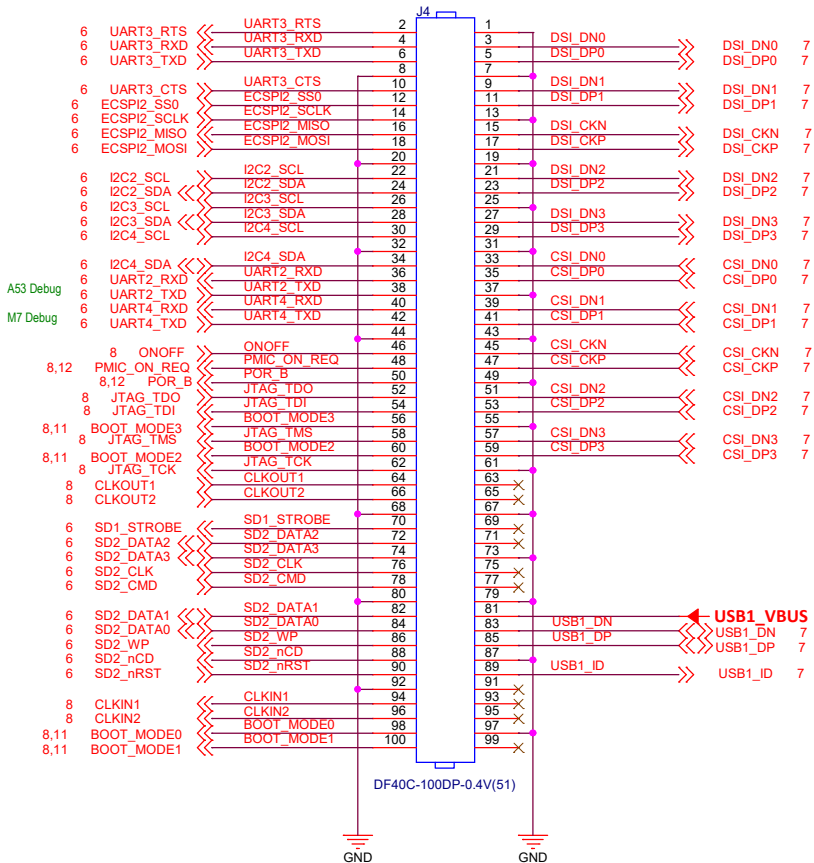
- Note:**
1. WDOG_B is used as Cold Reset, external pull up is needed. On EVK, R106 is not necessary, since WDOG_B/GPIO1_IO02 of CPU has internal pull up.
 2. PMIC_nINT is ppen drain output, external pull up is needed. On EVK, R61 is not necessary, since PMIC_nINT/GPIO1_IO03 of CPU has internal pull up.
 3. AGND/BUCK_AGND should be connected to ground plane through Via. Do not short to EP directly on top layer

SEQ	PWR/Signal	REG	MIN	TYP	MAX	Max Current(mA)
1	NVCC_SNVS_1V8	LDO1	1.62	1.8	1.98	10
2	VDD_SNVS_OV8	LDO2	0.76	0.8	0.9	10
3	RTC_RESET_B	RTC_RESET_B	--	--	--	--
4	CLK_32K_OUT	RTC_CLK	--	--	--	--
5	VDD_SOC&DRAM&PU_OV9	BUCK1	0.78/0.805	0.82/0.85	0.9	3000
6	VDD_ARM_OV9	BUCK2	0.805/0.9/0.95	0.85/0.95/1.0	0.95/1.0/1.05	3000
6	VDDA_1V8	LDO3	1.71	1.8	1.89	300
7	VDD_1V8/NVCC_1V8	BUCK5	1.65	1.8	1.95	2000
8	NVCC_DRAM_1V1	BUCK6	1.06	1.1	1.14	2000
9	VDD_3V3/NVCC_3V3	BUCK4	3	3.3	3.6	3000
9	NVCC_SD2	LDO5	3.0/1.65	3.3/1.8	3.6/1.95	150
10	POR_B	POR_B	--	--	--	--
11	VDD_PHY_1V2	LDO4	1.14	1.2	1.26	150

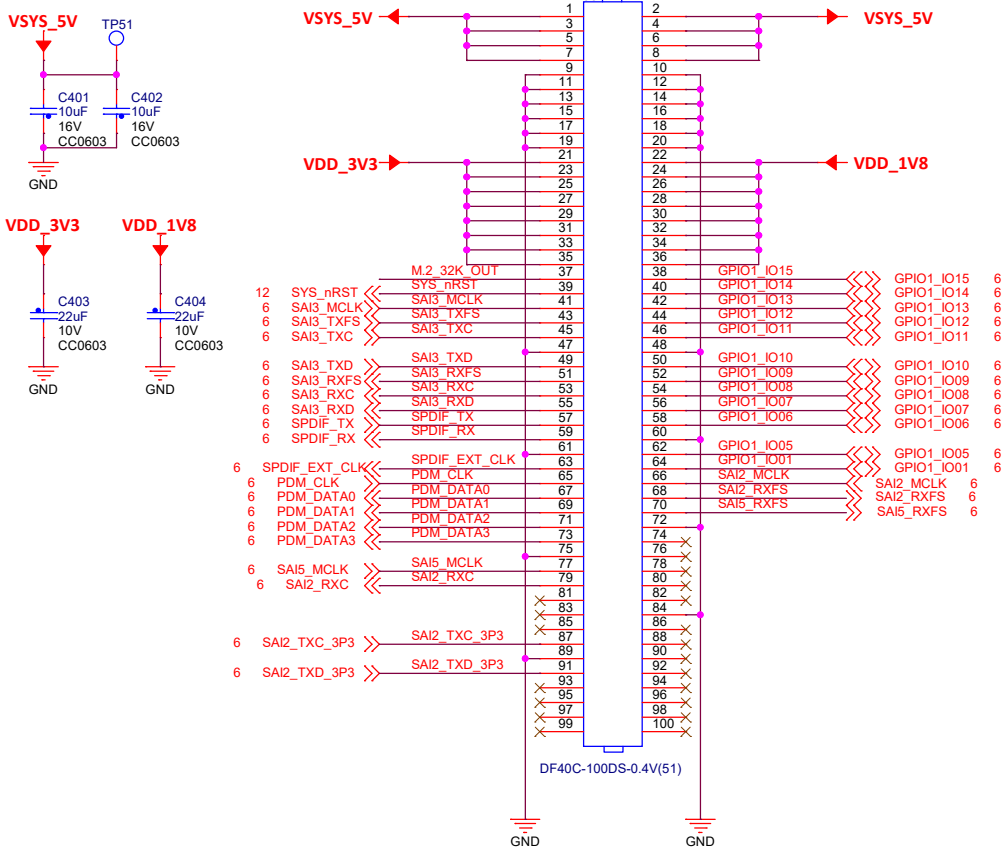
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B2B Connector for CPU Board

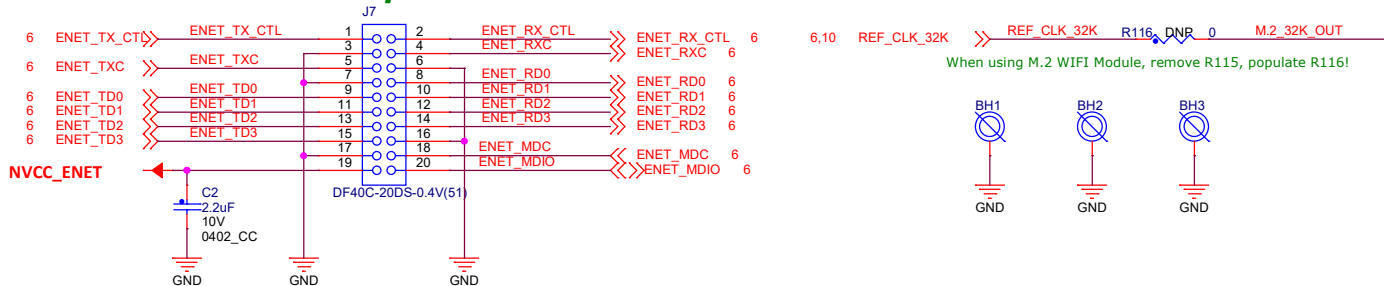
Header



Receptacle



Receptacle



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